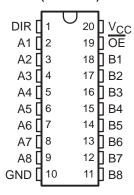
- B-Port Outputs Have Equivalent 25-Ω
   Series Resistors, So No External Resistors
   Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Impedance State During Power Up and Power Down
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

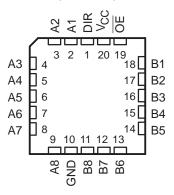
#### description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so the buses are effectively isolated.

SN54ABT2245 . . . J OR W PACKAGE SN74ABT2245 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT2245 . . . FK PACKAGE (TOP VIEW)



The B-port outputs, which are designed to sink up to 12 mA, include equivalent  $25-\Omega$  series resistors to reduce overshoot and undershoot.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2245 is characterized for operation from –40°C to 85°C.

#### **FUNCTION TABLE**

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

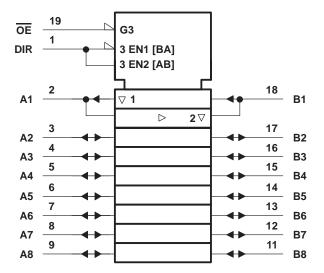


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

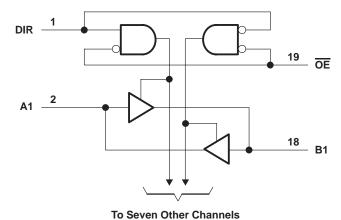
TEXAS INSTRUMENTS
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## logic symbol†



 $<sup>\</sup>ensuremath{^{\dagger}}$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

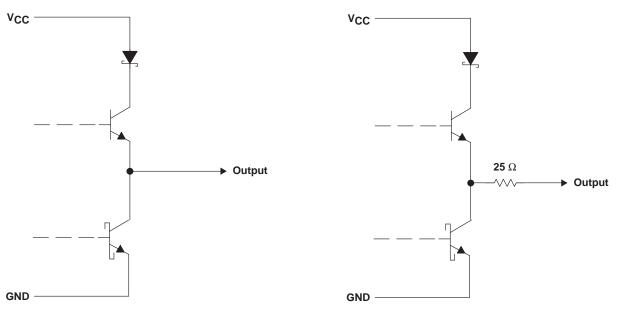
## logic diagram (positive logic)





#### schematic of A-port outputs

#### schematic of B-port outputs



All resistor values shown are nominal.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Current into any output in the low state, IO: SN54ABT2245 (except B port)	
SN74ABT2245 (except B port)	128 mA
B port	30 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DB package	
DW package	
N package	67°C/W
PW package	128°C/W
Storage temperature range, T <sub>stq</sub> 6	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



# SN54ABT2245, SN74ABT2245 OCTAL TRANSCEIVERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS SCBS234D – SEPTEMBER 1992 – REVISED MAY 1997

#### recommended operating conditions (see Note 3)

			SN54AE	3T2245	SN74AB	T2245	UNIT
		MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0	VCC	0	VCC	V
lou	High-level output current	A port		-24		-32	mA
ІОН	riigii-ievei output current	B port		-12		-12	IIIA
la.	Low-level output current	A port		48		64	mA
IOL	Low-level output current	B port		12		12	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
Δt/ΔVCC	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONF	NTIONS	T,	Δ = 25°C	;	SN54AE	T2245	SN74ABT2245		UNIT	
PAR	KAWETER	TEST COND	DITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	3.35			3.3		3.35			
	Prost	$V_{CC} = 5 V$ ,	$I_{OH} = -1 \text{ mA}$	3.85			3.8		3.85			
	B port	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -3 mA				3		3.1			
V		VCC = 4.5 V	I <sub>OH</sub> = -12 mA	2.6					2.6		\ \ \	
VOH		V <sub>CC</sub> = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		V	
	A nort	V <sub>CC</sub> = 5 V,	IOH = -3 mA	3			3		3			
	A port	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2					
		VCC = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2			
	B port		$I_{OL} = 8 \text{ mA}$			0.65		0.8		0.65		
Vo.	Броп	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	I <sub>OL</sub> = 12 mA			0.8				0.8	V	
VOL	A nort	VCC = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V	
	A port		I <sub>OL</sub> = 64 mA			0.55*				0.55		
V <sub>hys</sub>					100						mV	
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V}, \text{ V}_{I} = 0$	V <sub>CC</sub> or GND			±1		±1		±1		
lį	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$				±20		±20		±20	μΑ	
I <sub>OZH</sub> ‡		$V_{CC} = 2.1 \text{ V} \text{ to } 5.5 \text{ V},$ $V_{O} = 2.7 \text{ V}, \text{ OE } \ge 2 \text{ V}$				10		10		10	μΑ	
I <sub>OZL</sub> ‡		$V_{CC} = 2.1 \text{ V} \text{ to } 5.5 \text{ V},$ $V_{O} = 0.5 \text{ V}, \overline{OE} \ge 2 \text{ V}$				-10		-10		-10	μΑ	
IOZPU§		$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{\text{OR}}$	= x			±50		±50		±50	μΑ	
I <sub>OZPD</sub> §		$V_{CC} = 2.1 \text{ V to 0},$ $V_{O} = 0.5 \text{ V to 2.7 V}, \overline{OR}$				±50		±50		±50	μΑ	
I <sub>off</sub>		$V_{CC} = 0,$	V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V			±100	<del>                                     </del>		<del>                                     </del>	±100	μА	
ICEX	Outputs high	V <sub>CC</sub> = 5,5 V,	V <sub>O</sub> = 5.5 V			50		50	$\vdash$	50	μΑ	
·CLX	B port	7,00 0.0 1,		-25	-	-100	-25	-100	-25	-100	po t	
IO¶	A port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
$\overline{}$		V 55V	Outputs high		1	250	<u> </u>	250		250	μΑ	
Icc	A or B ports	$V_{CC} = 5.5 \text{ V},$ $I_{C} = 0,$	Outputs low		24	32		32		32	mA	
	, , , , ,	$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ	
	VCC = 5.5 V, One input at 3.4 V,		Outputs enabled			1.5		1.5		1.5	-	
∆lcc#	Data inputs	Other inputs at V <sub>CC</sub> or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V <sub>CC</sub> = 5.5 V, One inpu Other inputs at V <sub>CC</sub> or				1.5		1.5		1.5		
C <sub>i</sub>		V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
		V <sub>O</sub> = 2.5 V or 0.5 V			6						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.



<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

<sup>§</sup> This parameter is characterized but not production tested.

 $<sup>\</sup>P$  Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

## SN54ABT2245, SN74ABT2245 OCTAL TRANSCEIVERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

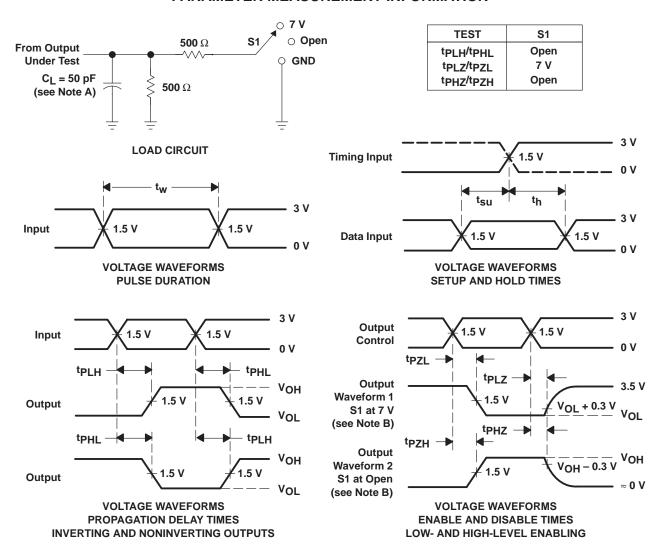
SCBS234D - SEPTEMBER 1992 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54AB	T2245	SN74AB	UNIT		
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
<sup>t</sup> PLH	А	В	1	2.5	3.4	1	4	1	3.8	ns	
<sup>t</sup> PHL		Ь	1	3.2	4.2	1	4.6	1	4.5	115	
<sup>t</sup> PLH	В	А	1	2.2	3.2	1	3.8	1	3.6	20	
<sup>t</sup> PHL	В	A	1	2.7	3.6	1	4.2	1	4	ns	
<sup>t</sup> PZH	ŌĒ	А	1	3.3	4.6	1	5.6	1	5.5	ns	
t <sub>PZL</sub>	OE OE	A	1	3.2	4.7	1	6	1	5.7	115	
<sup>t</sup> PHZ	ŌĒ	А	2	4	5.1	2	5.7	2	5.6	ns	
t <sub>PLZ</sub>		A	1	2.9	4	1	4.6	1	4.5	115	
<sup>t</sup> PZH		D	1.5	3.6	4.9	1.5	6.3	1.5	6.1		
t <sub>PZL</sub>	ŌĒ	В	1.5	3.9	5.3	1.5	6.6	1.5	6.3	ns	
<sup>t</sup> PHZ		В	1.5	3.6	4.7	1.5	5.5	1.5	5.3		
<sup>t</sup> PLZ	OE	ŌĒ	В В	1.5	3.3	4.4	1.5	4.9	1.5	4.8	ns



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9560601Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9560601Q2A SNJ54 ABT2245FK	Samples
5962-9560601QRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9560601QR A SNJ54ABT2245J	Samples
5962-9560601QSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9560601QS A SNJ54ABT2245W	Samples
SN74ABT2245DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245DBRG4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT2245N	Samples
SN74ABT2245PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SNJ54ABT2245FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9560601Q2A SNJ54 ABT2245FK	Samples
SNJ54ABT2245J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9560601QR A SNJ54ABT2245J	Samples
SNJ54ABT2245W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9560601QS A SNJ54ABT2245W	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

### PACKAGE OPTION ADDENDUM

www.ti.com 25-Oct-2024

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ABT2245, SN74ABT2245:

Catalog: SN74ABT2245

Military: SN54ABT2245

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

## **PACKAGE OPTION ADDENDUM**

www.ti.com 25-Oct-2024

• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT2245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 5-Dec-2023



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2245DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74ABT2245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABT2245PWR	TSSOP	PW	20	2000	356.0	356.0	35.0

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 5-Dec-2023

#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9560601Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9560601QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ABT2245DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT2245N	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT2245PW	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54ABT2245FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ABT2245W	W	CFP	20	25	506.98	26.16	6220	NA

## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## W (R-GDFP-F20)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

  D. Index point is provided on cap for terminal identification only.

  E. Falls within Mil—Std 1835 GDFP2—F20







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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